

Educational Background

The Hong Kong University of Science and Technology 09/2023-Now

PhD, major in **Electronic and Computer Engineering**

Supervisor: Prof. Wei ZHANG

Research Topic: Computer Architecture, Design Automation

The Hong Kong University of Science and Technology 09/2021-08/2023

MPhil, major in **Microelectronics**

Supervisor: Prof. Wei ZHANG

Thesis Title: Bayesian Optimization with Clustering and Rollback for CNN Auto Pruning

The Hong Kong University of Science and Technology 09/2019-06/2020

MSc, major in **Electronic Engineering**

Beijing Institute of Technology 09/2015-06/2019

BEng, major in **Automation**

Graduation Project: Three Phase T-NPC Electrical Load Simulator based on FPGA-DSP Microcontroller

Work Experiences

Research Intern - Computing Technology Lab, Alibaba DAMO Academy 06/2022-12/2022

- Explainable machine learning for micro-architecture design space exploration
- Cost-aware neural architecture search

Research Assistant - Reconfigurable Computing Systems Lab, HKUST 09/2020-08/2021

- Large-scale system verification framework
- A Bayesian optimization framework for CNN auto compression

Publications

[4] Explainable Fuzzy Neural Network with Multi-Fidelity Reinforcement Learning for Micro-Architecture Design Space Exploration

Hanwei Fan, Ya Wang, Sicheng Li, Tingyuan Liang, Wei Zhang

accepted by ACM/IEEE Design Automation Conference (DAC), 2024

[3] A Modular Branch Predictor Performance Analysis Framework for Fast Design Space Exploration

Ya Wang, **Hanwei Fan**, Sicheng Li, Tingyuan Liang, Wei Zhang

accepted by IEEE/ACM Proceedings Design, Automation and Test in Europe (DATE), 2024

[2] ASAP: Accurate Synthesis Analysis and Prediction with Multi-Task Learning (**Best Paper**)

Yikang Ouyang, Sicheng Li, Dongsheng Zuo, **Hanwei Fan**, Yuzhe Ma

ACM/IEEE 5th Workshop on Machine Learning for CAD (MLCAD), 2023

[1] Bayesian Optimization with Clustering and Rollback for CNN Auto Pruning

Hanwei Fan, Jiandong Mu, Wei Zhang

European Conference on Computer Vision (ECCV), 2022